Integrated Device Technology, Inc.
2975 Stender Way, Santa Clara, CA - 95054

PRODUCT/PROCESS CHANGE NOTICE (PCN)

PCN #: **L0203-03** DATE: March 15, 2002
Product Affected: IDT74ALVCF162835
IDT74ALVCHS162830, IDTCSP2510

Date Effective: June 15, 2002

MEANS OF DISTINGUISHING CHANGED DEVICES:
☐ Product Mark
☐ Back Mark
■ Date Code Top mark will have "4" following the die revision.
☐ Other

Contact: Bimla Paul
Title: Quality Assurance Manager
Phone #: (408)-654-6419
Fax #: (408)-492-8362
E-mail: bimla.paul@idt.com

Attachment:: ■ Yes ☐ No

Samples: Available upon request.

DESCRIPTION AND PURPOSE OF CHANGE:

- ☐ Die Technology
- ☐ Wafer Fabrication Process
- ☐ Assembly Process
- ☐ Equipment
- ☐ Material
- ☐ Testing
- ■ Manufacturing Site
- ☐ Data Sheet
- ☐ Other

To consolidate wafer fab production from Salinas, California (Fab 2) to Hillsboro, Oregon (Fab 4), these qualified Logic products will be transferred to IDT's wafer fab facility in Hillsboro, Oregon. There is no change in die technology.

RELIABILITY/QUALIFICATION SUMMARY:

Qualification testing will verify that there is no change to the product reliability. Please see attachment for qualification detail.

CUSTOMER ACKNOWLEDGMENT OF RECEIPT:

IDT records indicate that you require written notification of this change. Please use the acknowledgement below or E-Mail to grant approval or request additional information. If IDT does not receive acknowledgement within 30 days of this notice it will be assumed that this change is acceptable.
IDT reserves the right to ship either version manufactured after the process change effective date until the inventory on the earlier version has been depleted.

Customer: ____________________

☐ ***Approval for shipments prior to effective date.***

Name/Date: ____________________

E-Mail Address: ____________________

Title: ____________________

Phone# /Fax# : ____________________

CUSTOMER COMMENTS: ____________________

IDT ACKNOWLEDGMENT OF RECEIPT:

RECD. BY: ____________________ DATE: ____________________

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ATTACHMENT - PCN #: L0203-03

PCN Type: Fab Site Change

Data Sheet Change: None

Detail of Change: Transfer existing qualified products from Salinas, California Wafer Fab Facility (Fab 2) to Hillsboro, Oregon Wafer Fab Facility (Fab 4).

Part Number	Current Wafer Fab				Transfer Wafer Fab			
	Manufacturing Site	Technology	Wafer Size	Die Revision	Manufacturing Site	Technology	Wafer Size	Die Revision
IDT74ALVCF162835	Salinas, CA	CMOS 8	6 inch	A	Hillsboro, OR	CMOS 8	8 inch	A4
IDT74ALVCHS162830	Salinas, CA	CMOS 8	6 inch	AB	Hillsboro, OR	CMOS 8	8 inch	AB4
IDTCSP2510	Salinas, CA	CMOS 8	6 inch	Z	Hillsboro, OR	CMOS 8	8 inch	Z4

Note: There is no change in die technology.

Conversion schedule (Estimated)

Base Device	Sample Availability	Production Shipments
IDT74ALVCF162835	Now	June 15, 2002
IDT74ALVCHS162830	April 17, 2002	June 15, 2002
IDTCSP2510	Now	June 15, 2002

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Qualification Plan: QLG-02-07/QLG-02-08

		Test Results		
	Required Sample/ # Fails	74ALVCF162835	74ALVCHS162830 Expected 5/31/02	CSP2510 Expected 5/31/02
Operating Life Test: Dynamic 1000 hrs @ 125°C or equivalent	116/0	116/0		
Bake & Ballshear Test @ 200°C / 4 ball bonds per device	5/0	5/0		
Temperature Cycling: (-65°C to +150°C, 500 cycles)	45/0	45/0		
HAST: (Biased, 100 Hrs. @ +130°C, +85%RH)	45/0	45/0		
ESD Human Body Model	3/0	3/0		
ESD Charged Device Model	3/0	3/0		
ESD Machine Model	3/0	3/0		
Latch up: (Tested to 1.5X Vcc)	10/0	10/0		

Characterization Data:

Characterization data is available upon request.